

## **Thermal comfort models: a review and numerical investigation**

Cheng Y, Niu J, Gao N.

Building and environment

2012; 47:13-22

### **ARTICLE IDENTIFIERS**

DOI: 10.1016/j.buildenv.2011.05.011

PMID: unavailable

PMCID: not available

### **JOURNAL IDENTIFIERS**

LCCN: 78649044

pISSN: 0360-1323

eISSN: 1873-684X

OCLC ID: 02177041

CONS ID: sc 78001758

US National Library of Medicine ID: 101562928

This article was identified from a query of the SafetyLit database.